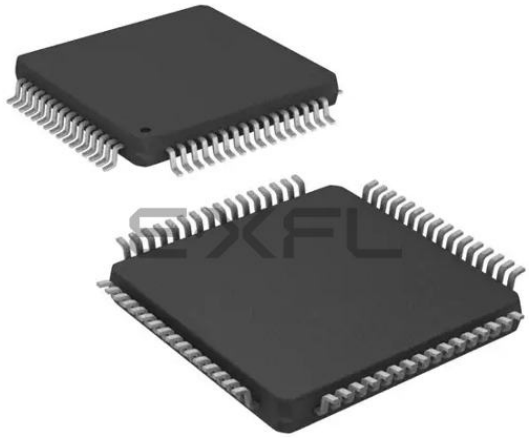

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	dsPIC
Core Size	16-Bit
Speed	20 MIPS
Connectivity	CANbus, I²C, SPI, UART/USART
Peripherals	AC'97, Brown-out Detect/Reset, I²S, LVD, POR, PWM, WDT
Number of I/O	52
Program Memory Size	144KB (48K x 24)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	A/D 16x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic30f6012at-20e-pt

FIGURE 2-2: DSP ENGINE BLOCK DIAGRAM

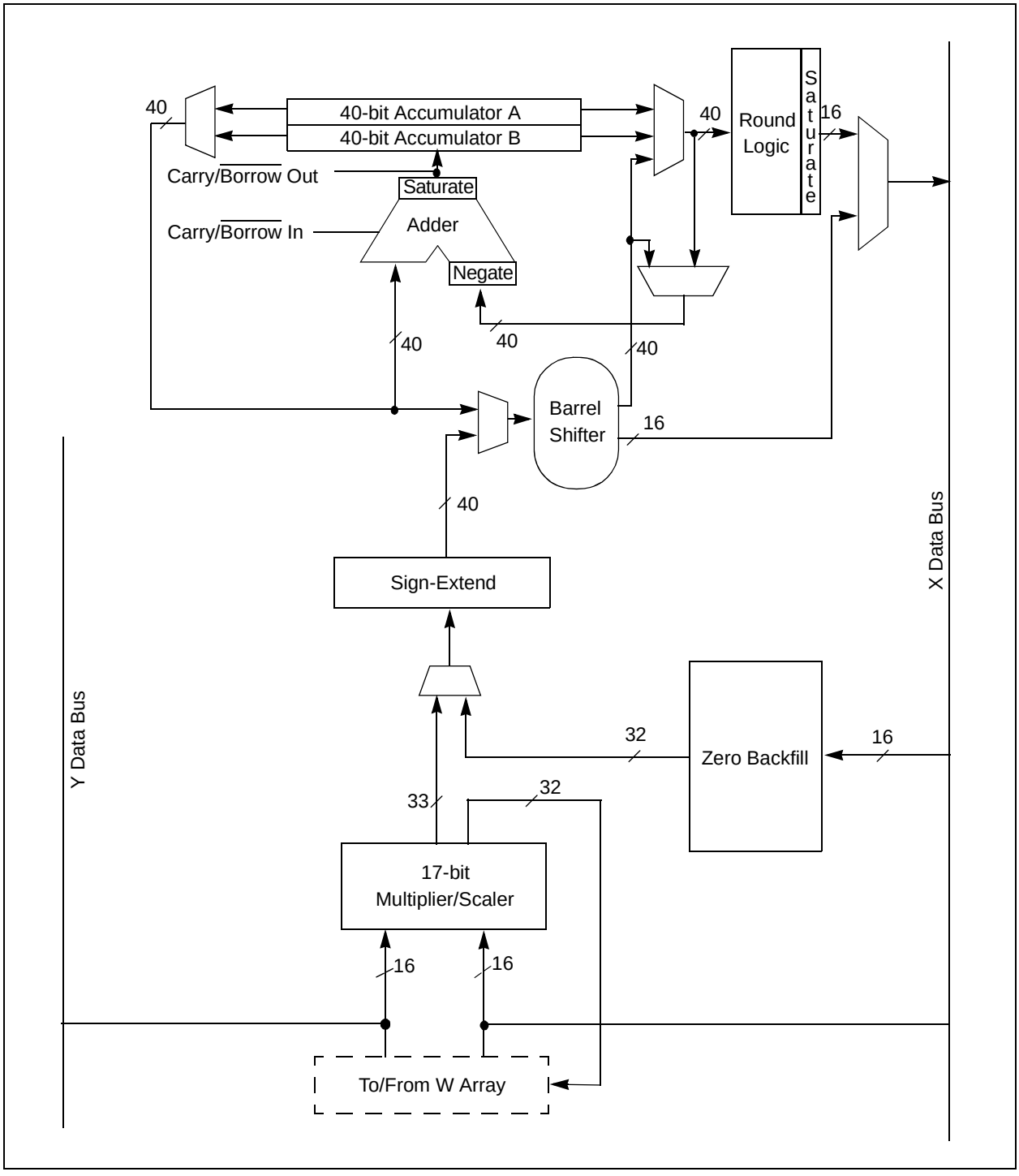


FIGURE 3-8: DATA SPACE MEMORY MAP FOR dsPIC30F6012A/6014A

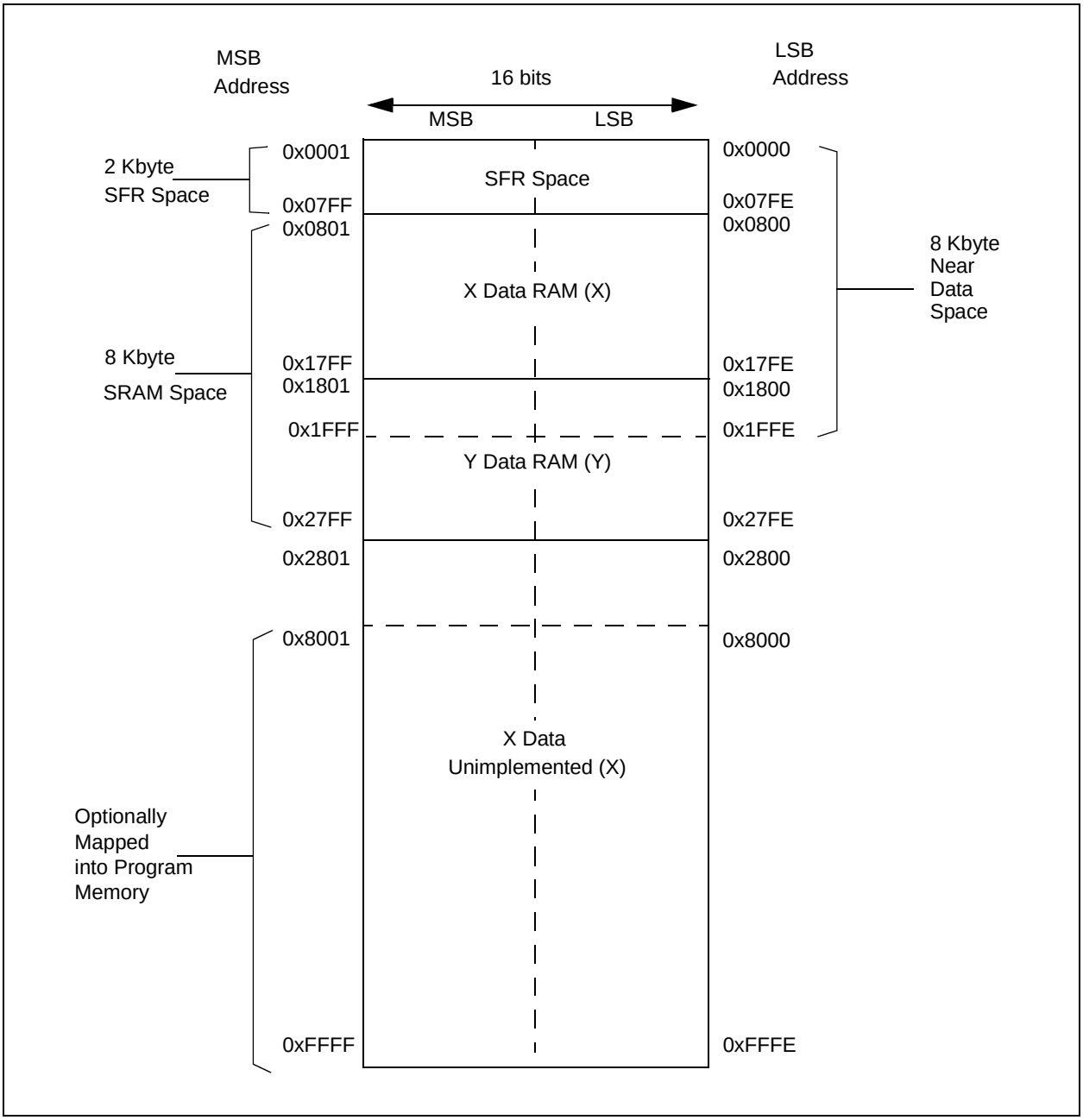


TABLE 3-3: CORE REGISTER MAP

SFR Name	Address (Home)	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset State
W0	0000	W0 / WREG																0000 0000 0000 0000
W1	0002	W1																0000 0000 0000 0000
W2	0004	W2																0000 0000 0000 0000
W3	0006	W3																0000 0000 0000 0000
W4	0008	W4																0000 0000 0000 0000
W5	000A	W5																0000 0000 0000 0000
W6	000C	W6																0000 0000 0000 0000
W7	000E	W7																0000 0000 0000 0000
W8	0010	W8																0000 0000 0000 0000
W9	0012	W9																0000 0000 0000 0000
W10	0014	W10																0000 0000 0000 0000
W11	0016	W11																0000 0000 0000 0000
W12	0018	W12																0000 0000 0000 0000
W13	001A	W13																0000 0000 0000 0000
W14	001C	W14																0000 0000 0000 0000
W15	001E	W15																0000 1000 0000 0000
SPLIM	0020	SPLIM																0000 0000 0000 0000
ACCAL	0022	ACCAL																0000 0000 0000 0000
ACCAH	0024	ACCAH																0000 0000 0000 0000
ACCAU	0026	Sign-Extension (ACCA<39>)								ACCAU								0000 0000 0000 0000
ACCBL	0028	ACCBL																0000 0000 0000 0000
ACCBH	002A	ACCBH																0000 0000 0000 0000
ACCBU	002C	Sign-Extension (ACCB<39>)								ACCBU								0000 0000 0000 0000
PCL	002E	PCL																0000 0000 0000 0000
PCH	0030	—	—	—	—	—	—	—	—	—	PCH							0000 0000 0000 0000
TBLPAG	0032	—	—	—	—	—	—	—	—	TBLPAG								0000 0000 0000 0000
PSVPAG	0034	—	—	—	—	—	—	—	—	PSVPAG								0000 0000 0000 0000
RCOUNT	0036	RCOUNT																uuuu uuuu uuuu uuuu
DCOUNT	0038	DCOUNT																uuuu uuuu uuuu uuuu
DOSTARTL	003A	DOSTARTL															0	uuuu uuuu uuuu uuu0
DOSTARTH	003C	—	—	—	—	—	—	—	—	—	DOSTARTH							0000 0000 0uuu uuuu
DOENDL	003E	DOENDL															0	uuuu uuuu uuuu uuu0
DOENDH	0040	—	—	—	—	—	—	—	—	—	DOENDH							0000 0000 0uuu uuuu

Legend: u = uninitialized bit

6.6 Programming Operations

A complete programming sequence is necessary for programming or erasing the internal Flash in RTSP mode. A programming operation is nominally 2 msec in duration and the processor stalls (waits) until the operation is finished. Setting the WR bit (NVMCON<15>) starts the operation, and the WR bit is automatically cleared when the operation is finished.

6.6.1 PROGRAMMING ALGORITHM FOR PROGRAM FLASH

The user can erase and program one row of program Flash memory at a time. The general process is:

1. Read one row of program Flash (32 instruction words) and store into data RAM as a data “image”.
2. Update the data image with the desired new data.
3. Erase program Flash row.
   a) Setup NVMCON register for multi-word, program Flash, erase, and set WREN bit.
   b) Write address of row to be erased into NVMADRU/NVMADR.
   c) Write ‘55’ to NVMKEY.
   d) Write ‘AA’ to NVMKEY.
   e) Set the WR bit. This will begin erase cycle.
   f) CPU will stall for the duration of the erase cycle.
   g) The WR bit is cleared when erase cycle ends.
4. Write 32 instruction words of data from data RAM “image” into the program Flash write latches.
5. Program 32 instruction words into program Flash.
   a) Setup NVMCON register for multi-word, program Flash, program, and set WREN bit.
   b) Write ‘55’ to NVMKEY.
   c) Write ‘AA’ to NVMKEY.
   d) Set the WR bit. This will begin program cycle.
   e) CPU will stall for duration of the program cycle.
   f) The WR bit is cleared by the hardware when program cycle ends.
6. Repeat steps 1 through 5 as needed to program desired amount of program Flash memory.

6.6.2 ERASING A ROW OF PROGRAM MEMORY

Example 6-1 shows a code sequence that can be used to erase a row (32 instructions) of program memory.

EXAMPLE 6-1: ERASING A ROW OF PROGRAM MEMORY

```
; Setup NVMCON for erase operation, multi word write
; program memory selected, and writes enabled
        MOV     #0x4041,W0                  ;
        MOV     W0,NVMCON                   ; Init NVMCON SFR
; Init pointer to row to be ERASED
        MOV     #tblpage(PROG_ADDR),W0      ;
        MOV     W0,NVMADRU                  ; Initialize PM Page Boundary SFR
        MOV     #tbloffset(PROG_ADDR),W0    ; Intialize in-page EA[15:0] pointer
        MOV     W0, NVMADR                  ; Initialize NVMADR SFR
        DISI    #5                          ; Block all interrupts with priority <7 for
                                            ; next 5 instructions
        MOV     #0x55,W0
        MOV     W0,NVMKEY                   ; Write the 0x55 key
        MOV     #0xAA,W1                    ;
        MOV     W1,NVMKEY                   ; Write the 0xAA key
        BSET    NVMCON,#WR                  ; Start the erase sequence
        NOP                                 ; Insert two NOPs after the erase
        NOP                                 ; command is asserted
```

8.0 I/O PORTS

Note: This data sheet summarizes features of this group of dsPIC30F devices and is not intended to be a complete reference source. For more information on the CPU, peripherals, register descriptions and general device functionality, refer to the *dsPIC30F Family Reference Manual* (DS70046).

All of the device pins (except VDD, VSS, $\overline{\text{MCLR}}$ and OSC1/CLKI) are shared between the peripherals and the parallel I/O ports.

All I/O input ports feature Schmitt Trigger inputs for improved noise immunity.

8.1 Parallel I/O (PIO) Ports

When a peripheral is enabled and the peripheral is actively driving an associated pin, the use of the pin as a general purpose output pin is disabled. The I/O pin may be read but the output driver for the parallel port bit will be disabled. If a peripheral is enabled but the peripheral is not actively driving a pin, that pin may be driven by a port.

All port pins have three registers directly associated with the operation of the port pin. The Data Direction register (TRISx) determines whether the pin is an input or an output. If the data direction bit is a '1', then the pin is an input. All port pins are defined as inputs after a Reset. Reads from the latch (LATx), read the latch. Writes to the latch, write the latch (LATx). Reads from the port (PORTx), read the port pins and writes to the port pins, write the latch (LATx).

Any bit and its associated data and control registers that are not valid for a particular device will be disabled. That means the corresponding LATx and TRISx registers and the port pin will read as zeros.

When a pin is shared with another peripheral or function that is defined as an input only, it is nevertheless regarded as a dedicated port because there is no other competing source of outputs. An example is the INT4 pin.

The format of the registers for PORTA are shown in Table 8-1.

The TRISA (Data Direction Control) register controls the direction of the RA<7:0> pins, as well as the INTx pins and the VREF pins. The LATA register supplies data to the outputs and is readable/writable. Reading the PORTA register yields the state of the input pins, while writing the PORTA register modifies the contents of the LATA register.

A parallel I/O (PIO) port that shares a pin with a peripheral is, in general, subservient to the peripheral. The peripheral's output buffer data and control signals are provided to a pair of multiplexers. The multiplexers select whether the peripheral or the associated port has ownership of the output data and control signals of the I/O pad cell. Figure 8-2 shows how ports are shared with other peripherals and the associated I/O cell (pad) to which they are connected. Table 8-2 through Table 8-9 show the formats of the registers for the shared ports, PORTB through PORTG.

Note: The actual bits in use vary between devices.

FIGURE 8-1: BLOCK DIAGRAM OF A DEDICATED PORT STRUCTURE

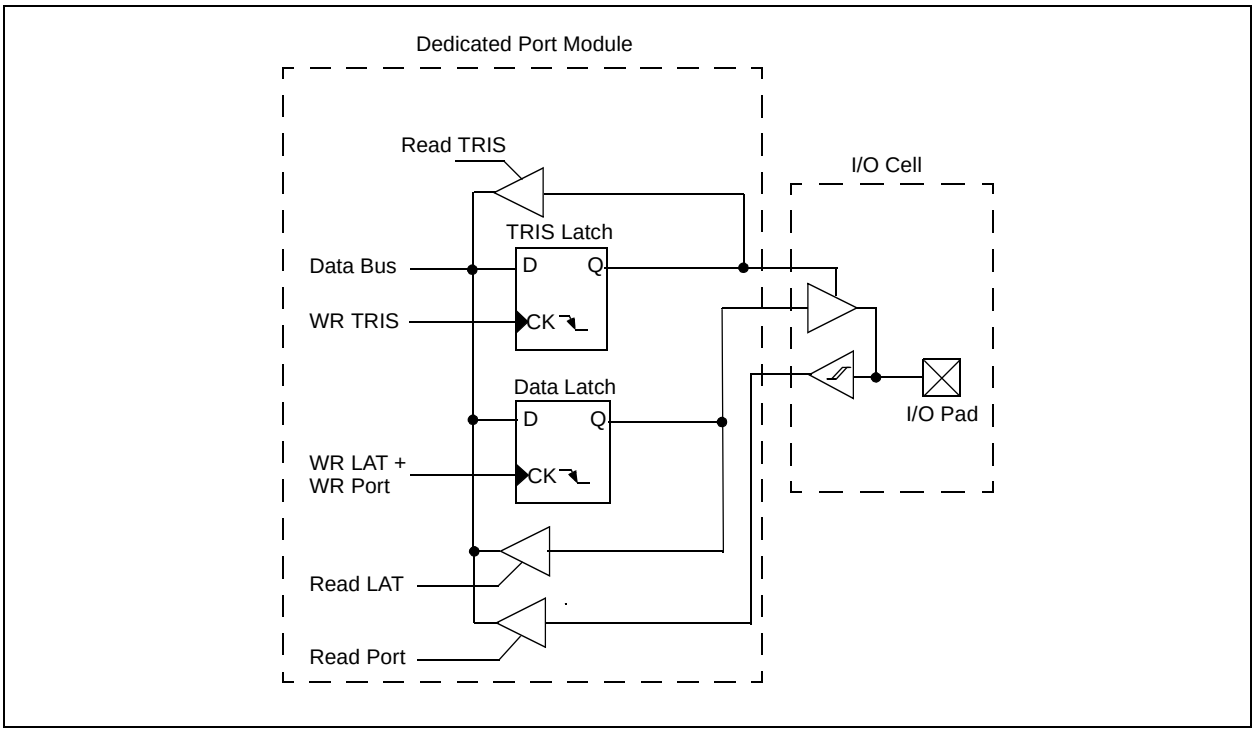


TABLE 9-1: TIMER1 REGISTER MAP

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset State
TMR1	0100	Timer1 Register																uuuu uuuu uuuu uuuu
PR1	0102	Period Register 1																1111 1111 1111 1111
T1CON	0104	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS1	TCKPS0	—	TSYNC	TCS	—	0000 0000 0000 0000

Legend: u = uninitialized bit

Note: Refer to *dsPIC30F Family Reference Manua*l (DS70046) for descriptions of register bit fields.

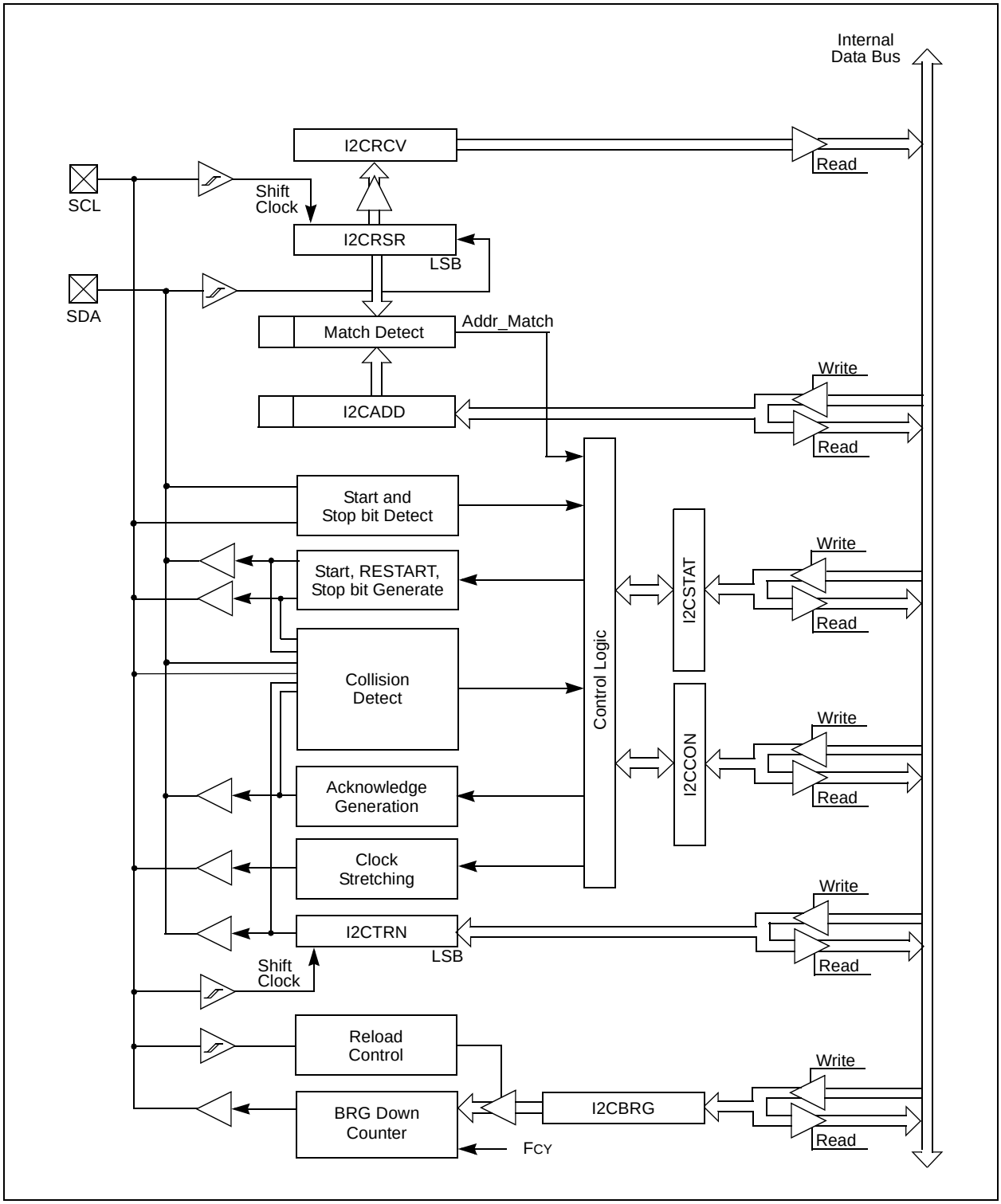
TABLE 13-1: OUTPUT COMPARE REGISTER MAP

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset State
OC1RS	0180	Output Compare 1 Secondary Register																0000 0000 0000 0000
OC1R	0182	Output Compare 1 Main Register																0000 0000 0000 0000
OC1CON	0184	—	—	OCSIDL	—	—	—	—	—	—	—	—	OCFLT	OCTSEL	OCM<2:0>			0000 0000 0000 0000
OC2RS	0186	Output Compare 2 Secondary Register																0000 0000 0000 0000
OC2R	0188	Output Compare 2 Main Register																0000 0000 0000 0000
OC2CON	018A	—	—	OCSIDL	—	—	—	—	—	—	—	—	OCFLT	OCTSE	OCM<2:0>			0000 0000 0000 0000
OC3RS	018C	Output Compare 3 Secondary Register																0000 0000 0000 0000
OC3R	018E	Output Compare 3 Main Register																0000 0000 0000 0000
OC3CON	0190	—	—	OCSIDL	—	—	—	—	—	—	—	—	OCFLT	OCTSEL	OCM<2:0>			0000 0000 0000 0000
OC4RS	0192	Output Compare 4 Secondary Register																0000 0000 0000 0000
OC4R	0194	Output Compare 4 Main Register																0000 0000 0000 0000
OC4CON	0196	—	—	OCSIDL	—	—	—	—	—	—	—	—	OCFLT	OCTSEL	OCM<2:0>			0000 0000 0000 0000
OC5RS	0198	Output Compare 5 Secondary Register																0000 0000 0000 0000
OC5R	019A	Output Compare 5 Main Register																0000 0000 0000 0000
OC5CON	019C	—	—	OCSIDL	—	—	—	—	—	—	—	—	OCFLT	OCTSEL	OCM<2:0>			0000 0000 0000 0000
OC6RS	019E	Output Compare 6 Secondary Register																0000 0000 0000 0000
OC6R	01A0	Output Compare 6 Main Register																0000 0000 0000 0000
OC6CON	01A2	—	—	OCSIDL	—	—	—	—	—	—	—	—	OCFLT	OCTSEL	OCM<2:0>			0000 0000 0000 0000
OC7RS	01A4	Output Compare 7 Secondary Register																0000 0000 0000 0000
OC7R	01A6	Output Compare 7 Main Register																0000 0000 0000 0000
OC7CON	01A8	—	—	OCSIDL	—	—	—	—	—	—	—	—	OCFLT	OCTSEL	OCM<2:0>			0000 0000 0000 0000
OC8RS	01AA	Output Compare 8 Secondary Register																0000 0000 0000 0000
OC8R	01AC	Output Compare 8 Main Register																0000 0000 0000 0000
OC8CON	01AE	—	—	OCSIDL	—	—	—	—	—	—	—	—	OCFLT	OCTSEL	OCM<2:0>			0000 0000 0000 0000

Legend: u = uninitialized bit

Note: Refer to *dsPIC30F Family Reference Manua*l (DS70046) for descriptions of register bit fields.

FIGURE 15-2: I^2C™ BLOCK DIAGRAM



16.0 UNIVERSAL ASYNCHRONOUS RECEIVER TRANSMITTER (UART) MODULE

Note: This data sheet summarizes features of this group of dsPIC30F devices and is not intended to be a complete reference source. For more information on the CPU, peripherals, register descriptions and general device functionality, refer to the *dsPIC30F Family Reference Manual* (DS70046).

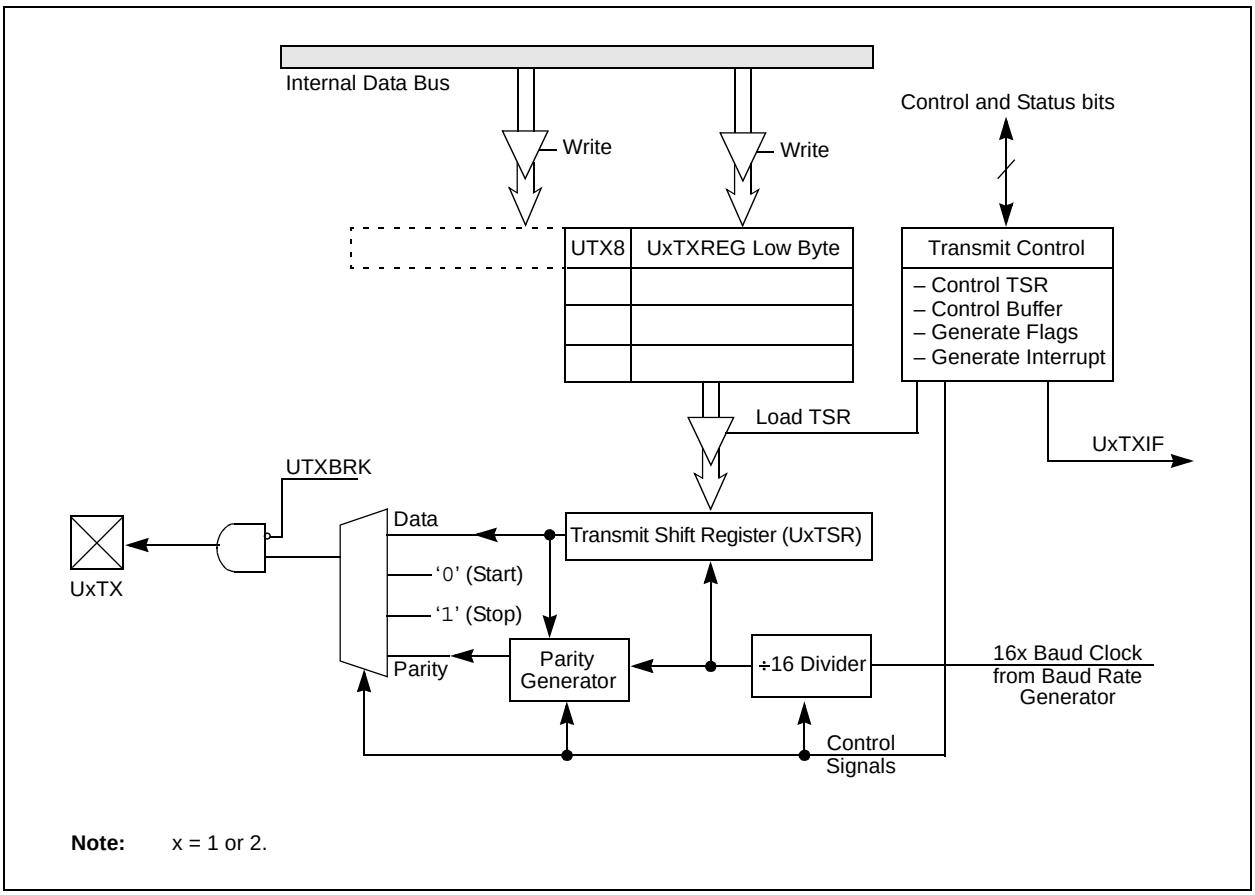
This section describes the Universal Asynchronous Receiver Transmitter communications module.

16.1 UART Module Overview

The key features of the UART module are:

- Full-duplex, 8 or 9-bit data communication
- Even, odd or no parity options (for 8-bit data)
- One or two Stop bits
- Fully integrated Baud Rate Generator with 16-bit prescaler
- Baud rates range from 38 bps to 1.875 Mbps at a 30 MHz instruction rate
- 4-word deep transmit data buffer
- 4-word deep receive data buffer
- Parity, framing and buffer overrun error detection
- Support for interrupt only on address detect (9th bit = 1)
- Separate transmit and receive interrupts
- Loopback mode for diagnostic support

FIGURE 16-1: UART TRANSMITTER BLOCK DIAGRAM



Note: x = 1 or 2.

18.3 DCI Module Operation

18.3.1 MODULE ENABLE

The DCI module is enabled or disabled by setting/clearing the DCIEN control bit in the DCICON1 SFR. Clearing the DCIEN control bit has the effect of resetting the module. In particular, all counters associated with CSCK generation, frame sync, and the DCI buffer control unit are reset.

The DCI clocks are shutdown when the DCIEN bit is cleared.

When enabled, the DCI controls the data direction for the four I/O pins associated with the module. The Port, LAT and TRIS register values for these I/O pins are overridden by the DCI module when the DCIEN bit is set.

It is also possible to override the CSCK pin separately when the bit clock generator is enabled. This permits the bit clock generator to operate without enabling the rest of the DCI module.

18.3.2 WORD SIZE SELECTION BITS

The WS<3:0> word size selection bits in the DCICON2 SFR determine the number of bits in each DCI data word. Essentially, the WS<3:0> bits determine the counting period for a 4-bit counter clocked from the CSCK signal.

Any data length, up to 16-bits, may be selected. The value loaded into the WS<3:0> bits is one less the desired word length. For example, a 16-bit data word size is selected when WS<3:0> = 1111.

Note:	These WS<3:0> control bits are used only in the Multi-Channel and I^2S modes. These bits have no effect in AC-Link mode since the data slot sizes are fixed by the protocol.

18.3.3 FRAME SYNC GENERATOR

The frame sync generator (COFSG) is a 4-bit counter that sets the frame length in data words. The frame sync generator is incremented each time the word size counter is reset (refer to **Section 18.3.2 "Word Size Selection Bits"**). The period for the frame synchronization generator is set by writing the COFSG<3:0> control bits in the DCICON2 SFR. The COFSG period in clock cycles is determined by the following formula:

EQUATION 18-1: COFSG PERIOD

$$\text{Frame Length} = \text{Word Length} \bullet (\text{FSG Value} + 1)$$

Frame lengths, up to 16 data words, may be selected. The frame length in CSCK periods can vary up to a maximum of 256 depending on the word size that is selected.

Note:	The COFSG control bits will have no effect in AC-Link mode since the frame length is set to 256 CSCK periods by the protocol.

18.3.4 FRAME SYNC MODE CONTROL BITS

The type of frame sync signal is selected using the Frame Synchronization mode control bits (COFSM<1:0>) in the DCICON1 SFR. The following operating modes can be selected:

- Multi-Channel mode
- I^2S mode
- AC-Link mode (16-bit)
- AC-Link mode (20-bit)

The operation of the COFSM control bits depends on whether the DCI module generates the frame sync signal as a master device, or receives the frame sync signal as a slave device.

The master device in a DSP/Codec pair is the device that generates the frame sync signal. The frame sync signal initiates data transfers on the CSDI and CSDO pins and usually has the same frequency as the data sample rate (COFS).

The DCI module is a frame sync master if the COFSD control bit is cleared and is a frame sync slave if the COFSD control bit is set.

18.3.5 MASTER FRAME SYNC OPERATION

When the DCI module is operating as a frame sync master device (COFSD = 0), the COFSM mode bits determine the type of frame sync pulse that is generated by the frame sync generator logic.

A new COFS signal is generated when the frame sync generator resets to '0'.

In the Multi-Channel mode, the frame sync pulse is driven high for the CSCK period to initiate a data transfer. The number of CSCK cycles between successive frame sync pulses will depend on the word size and frame sync generator control bits. A timing diagram for the frame sync signal in Multi-Channel mode is shown in Figure 18-2.

In the AC-Link mode of operation, the frame sync signal has a fixed period and duty cycle. The AC-Link frame sync signal is high for 16 CSCK cycles and is low for 240 CSCK cycles. A timing diagram with the timing details at the start of an AC-Link frame is shown in Figure 18-3.

In the I^2S mode, a frame sync signal having a 50% duty cycle is generated. The period of the I^2S frame sync signal in CSCK cycles is determined by the word size and frame sync generator control bits. A new I^2S data transfer boundary is marked by a high-to-low or a low-to-high transition edge on the COFS pin.

19.9 Module Power-down Modes

The module has 2 internal Power modes.

When the ADON bit is '1', the module is in Active mode; it is fully powered and functional.

When ADON is '0', the module is in Off mode. The digital and analog portions of the circuit are disabled for maximum current savings.

In order to return to the Active mode from Off mode, the user must wait for the ADC circuitry to stabilize.

19.10 ADC Operation During CPU Sleep and Idle Modes

19.10.1 ADC OPERATION DURING CPU SLEEP MODE

When the device enters Sleep mode, all clock sources to the module are shutdown and stay at logic '0'.

If Sleep occurs in the middle of a conversion, the conversion is aborted. The converter will not continue with a partially completed conversion on exit from Sleep mode.

Register contents are not affected by the device entering or leaving Sleep mode.

The ADC module can operate during Sleep mode if the ADC clock source is set to RC (ADRC = 1). When the RC clock source is selected, the ADC module waits one instruction cycle before starting the conversion. This allows the SLEEP instruction to be executed which eliminates all digital switching noise from the conversion. When the conversion is complete, the CONV bit will be cleared and the result loaded into the ADCBUF register.

If the ADC interrupt is enabled, the device will wake-up from Sleep. If the ADC interrupt is not enabled, the ADC module will then be turned off, although the ADON bit will remain set.

19.10.2 ADC OPERATION DURING CPU IDLE MODE

The ADSIDL bit selects if the module will stop on Idle or continue on Idle. If ADSIDL = 0, the module will continue operation on assertion of Idle mode. If ADSIDL = 1, the module will stop on Idle.

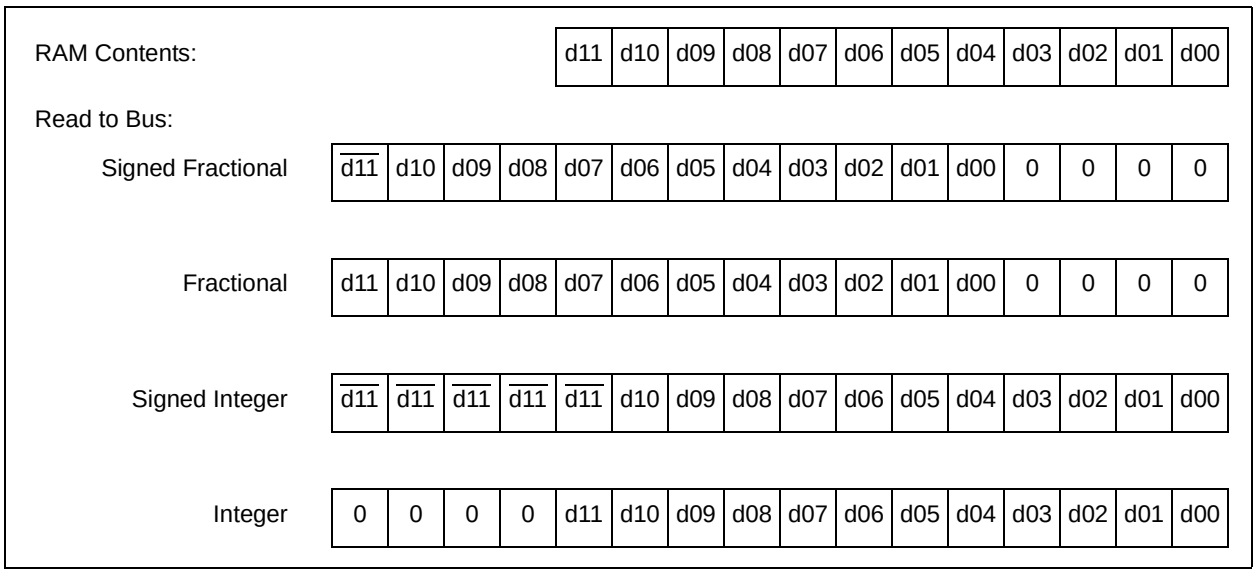
19.11 Effects of a Reset

A device Reset forces all registers to their Reset state. This forces the ADC module to be turned off, and any conversion and sampling sequence is aborted. The values that are in the ADCBUF registers are not modified. The ADC Result register will contain unknown data after a Power-on Reset.

19.12 Output Formats

The ADC result is 12 bits wide. The data buffer RAM is also 12 bits wide. The 12-bit data can be read in one of four different formats. The FORM<1:0> bits select the format. Each of the output formats translates to a 16-bit result on the data bus.

FIGURE 19-5: ADC OUTPUT DATA FORMATS



NOTES:

REGISTER 20-3: FOSC: OSCILLATOR CONFIGURATION REGISTER

Upper Byte:							
U	U	U	U	U	U	U	U
—	—	—	—	—	—	—	—
bit 23							bit 16

Middle Byte:							
R/P	R/P	U	U	U	R/P	R/P	R/P
FCKSM<1:0>		—	—	—	FOS<2:0>		
bit 15							bit 8

Lower Byte:							
U	U	U	R/P	R/P	R/P	R/P	R/P
—	—	—	FPR<4:0>				
bit 7							bit 0

bit 23-16 **Unimplemented:** Read as ‘0’

bit 15-14 **FCKSM<1:0>:** Clock Switching and Monitor Selection Configuration bits
1x = Clock switching is disabled, fail safe clock monitor is disabled
01 = Clock switching is enabled, fail safe clock monitor is disabled
00 = Clock switching is enabled, fail safe clock monitor is enabled

bit 13-10 **Unimplemented:** Read as ‘0’

bit 9-8 **FOS<2:0>:** Oscillator Group Selection on POR
111 = PLL Oscillator; PLL source selected by FPR<4:0> bits. See Table 20-2.
011 = EXT: External Oscillator; OSC1/OSC2 pins; External Oscillator configuration selected by FPR<4:0> bits
010 = LPRC: Internal Low-power RC
001 = FRC: Internal Fast RC
000 = LPOSC: Low-power Crystal Oscillator; SOSCI/SOSCO pins

bit 7-4 **Unimplemented:** Read as ‘0’

bit 3-0 **FPR<4:0>:** Oscillator Selection within Primary Group, see Table 20-2.

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’

TABLE 20-7: SYSTEM INTEGRATION REGISTER MAP FOR dsPIC30F601XA

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset State
RCON	0740	TRAPR	IOPUWR	BGST	LVDEN	LVDL<3:0>				EXTR	SWR	SWDTEN	WDTO	SLEEP	IDLE	BOR	POR	Depends on type of Reset.
OSCCON	0742	—	COSC<2:0>			—	NOSC<2:0>			POST<1:0>		LOCK	—	CF	—	LPOSCEN	OSWEN	Depends on Configuration bits.
OSCTUN	0744	—	—	—	—	—	—	—	—	—	—	—	—	TUN<3:0>				0000 0000 0000 0000
PMD1	0770	T5MD	T4MD	T3MD	T2MD	T1MD	—	—	DCIMD	I2CMD	U2MD	U1MD	SPI2MD	SPI1MD	C2MD	C1MD	ADCMD	0000 0000 0000 0000
PMD2	0772	IC8MD	IC7MD	IC6MD	IC5MD	IC4MD	IC3MD	IC2MD	IC1MD	OC8MD	OC7MD	OC6MD	OC5MD	OC4MD	OC3MD	OC2MD	OC1MD	0000 0000 0000 0000

Note: Refer to *dsPIC30F Family Reference Manual* (DS70046) for descriptions of register bit fields.

TABLE 20-8: DEVICE CONFIGURATION REGISTER MAP

File Name	Addr.	Bits 23-16	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
FOSC	F80000	—	FCKSM<1:0>		—	—	—	FOS<2:0>			—	—	—	FPR<4:0>				
FWDT	F80002	—	FWDTEN	—	—	—	—	—	—	—	—	—	FWPSA<1:0>		FWPSB<3:0>			
FBORPOR	F80004	—	MCLREN	—	—	—	—	PWMPIN	HPOL	LPOL	BOREN	—	BORV<1:0>		—	—	FPWRT<1:0>	
FGS	F8000A	—	—	—	—	—	—	—	—	—	—	—	—	—	—	GSS<1:0>		GWRP

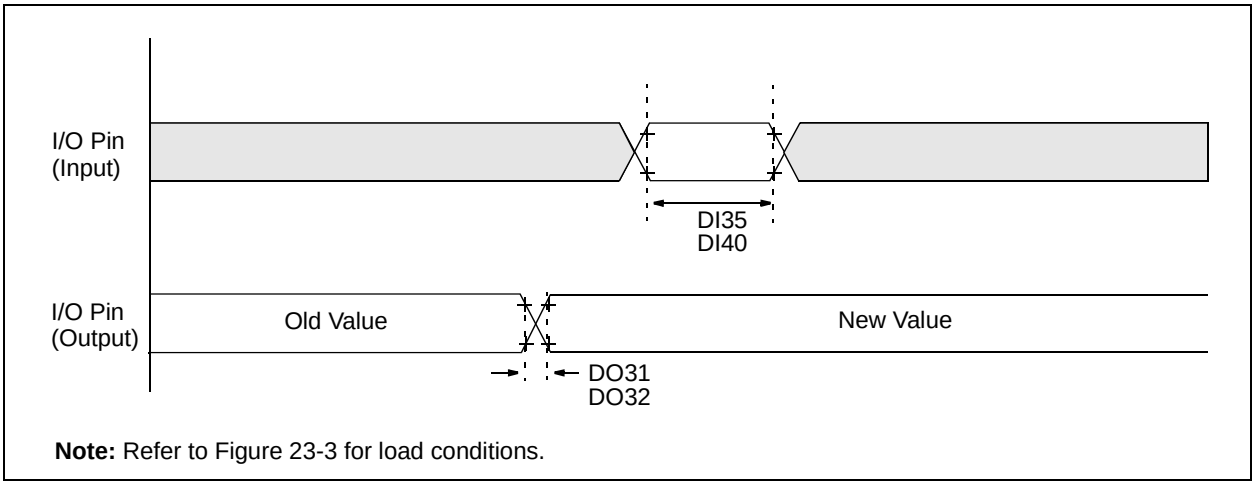
Note: Refer to *dsPIC30F Family Reference Manual* (DS70046) for descriptions of register bit fields.

TABLE 23-19: INTERNAL LPRC ACCURACY

AC CHARACTERISTICS		Standard Operating Conditions: 2.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
	LPRC @ Freq. = 512 kHz(1)					
OS65		-20	—	+40	%	—

Note 1: Change of LPRC frequency as VDD changes.

FIGURE 23-5: CLKOUT AND I/O TIMING CHARACTERISTICS



Note: Refer to Figure 23-3 for load conditions.

TABLE 23-20: CLKOUT AND I/O TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)(2)(3)**	**Min**	**Typ(4)**	**Max**	**Units**	**Conditions**
DO31	TIOR	Port output rise time	—	7	20	ns	—
DO32	TIOF	Port output fall time	—	7	20	ns	—
DI35	TINP	INTx pin high or low time (output)	20	—	—	ns	—
DI40	TRBP	CNx high or low time (input)	2 TCY	—	—	ns	—

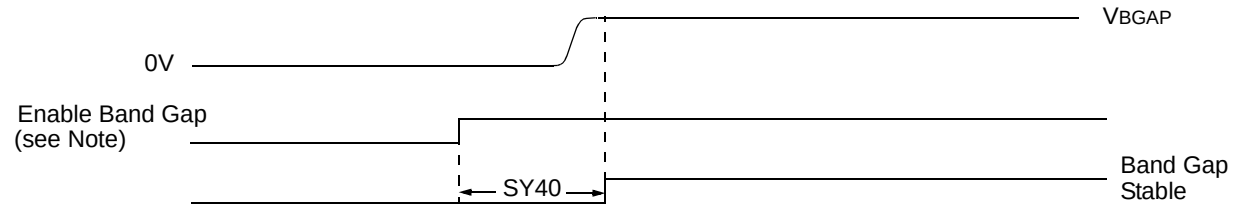
Note 1: These parameters are asynchronous events not related to any internal clock edges
2: Measurements are taken in RC mode and EC mode where CLKOUT output is 4 x TOSC.
3: These parameters are characterized but not tested in manufacturing.
4: Data in "Typ" column is at 5V, 25°C unless otherwise stated.

TABLE 23-21: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER AND BROWN-OUT RESET TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
SY10	TmcL	$\overline{\text{MCLR}}$ Pulse Width (low)	2	—	—	µs	-40°C to +85°C
SY11	TPWRT	Power-up Timer Period	3 12 50	4 16 64	6 22 90	ms	-40°C to +85°C User programmable
SY12	TPOR	Power On Reset Delay(3)	3	10	30	µs	-40°C to +85°C
SY13	TIOZ	I/O High-impedance from $\overline{\text{MCLR}}$ Low or Watchdog Timer Reset	—	0.8	1.0	µs	
SY20	TWDT1 TWDT2	Watchdog Timer Time-out Period (No Prescaler)	1.8 1.9	2.0 2.1	2.2 2.3	ms ms	VDD = 5V, -40°C to +85°C VDD = 3V, -40°C to +85°C
SY25	TBOR	Brown-out Reset Pulse Width(4)	100	—	—	µs	VDD ≤ VBOR (D034)
SY30	TOST	Oscillation Start-up Timer Period	—	1024 TOSC	—	—	TOSC = OSC1 period
SY35	TFSCM	Fail-Safe Clock Monitor Delay	—	500	900	µs	-40°C to +85°C

Note 1: These parameters are characterized but not tested in manufacturing.
2: Data in "Typ" column is at 5V, 25°C unless otherwise stated.
3: Characterized by design but not tested
4: Refer to Figure 23-2 and Table 23-11 for BOR.

FIGURE 23-7: BAND GAP START-UP TIME CHARACTERISTICS



Note: Set LVDEN bit (RCON<12>) or FBORPOR<7>set.

TABLE 23-22: BAND GAP START-UP TIME REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
SY40	TBGAP	Band Gap Start-up Time	—	40	65	µs	Defined as the time between the instant that the band gap is enabled and the moment that the band gap reference voltage is stable. RCON<13>Status bit

Note 1: These parameters are characterized but not tested in manufacturing.
2: Data in "Typ" column is at 5V, 25°C unless otherwise stated.

TABLE 23-38: 12-BIT ADC MODULE SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions: 2.7V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ**	**Max.**	**Units**	**Conditions**
Device Supply							
AD01	AVDD	Module VDD Supply	Greater of VDD - 0.3 or 2.7	—	Lesser of VDD + 0.3 or 5.5	V	—
AD02	AVSS	Module VSS Supply	VSS - 0.3	—	VSS + 0.3	V	—
Reference Inputs							
AD05	VREFH	Reference Voltage High	AVSS + 2.7	—	AVDD	V	—
AD06	VREFL	Reference Voltage Low	AVSS	—	AVDD - 2.7	V	—
AD07	VREF	Absolute Reference Voltage	AVSS - 0.3	—	AVDD + 0.3	V	—
AD08	IREF	Current Drain	—	150 .001	200 1	µA µA	operating off
Analog Input							
AD10	VINH-VINL	Full-Scale Input Span	VREFL		VREFH	V	See Note
AD11	VIN	Absolute Input Voltage	AVSS - 0.3		AVDD + 0.3	V	—
AD12	—	Leakage Current	—	±0.001	±0.610	µA	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 5V Source Impedance = 2.5 KΩ
AD13	—	Leakage Current	—	±0.001	±0.610	µA	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3V Source Impedance = 2.5 KΩ
AD15	RSS	Switch Resistance	—	3.2K	—	Ω	—
AD16	CSAMPLE	Sample Capacitor	—	18		pF	—
AD17	RIN	Recommended Impedance of Analog Voltage Source	—	—	2.5K	Ω	—
DC Accuracy							
AD20	Nr	Resolution	12 data bits			bits	
AD21	INL	Integral Nonlinearity	—	—	<±1	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 5V
AD21A	INL	Integral Nonlinearity	—	—	<±1	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3V
AD22	DNL	Differential Nonlinearity	—	—	<±1	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 5V
AD22A	DNL	Differential Nonlinearity	—	—	<±1	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3V
AD23	GERR	Gain Error	+1.25	+1.5	+3	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 5V
AD23A	GERR	Gain Error	+1.25	+1.5	+3	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3V

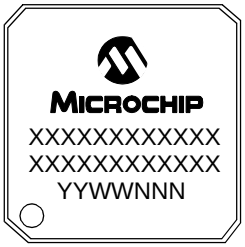
Note 1: The ADC conversion result never decreases with an increase in the input voltage, and has no missing codes.

2: Parameters are characterized but not tested. Use as design guidance only.

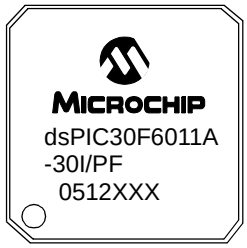
24.0 PACKAGING INFORMATION

24.1 Package Marking Information

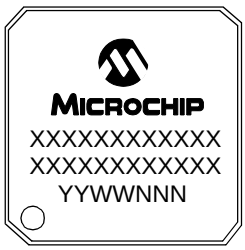
64-Lead TQFP



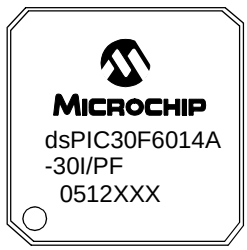
Example



80-Lead TQFP



Example

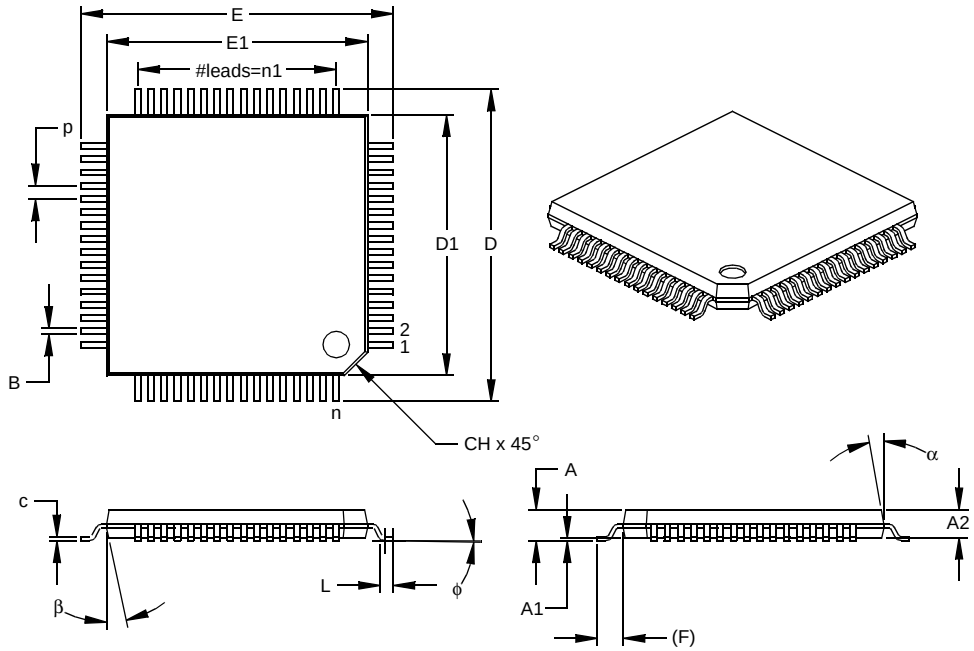


Legend:	XX...X	Customer specific information*
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line thus limiting the number of available characters for customer specific information.

***** Standard device marking consists of Microchip part number, year code, week code, and traceability code. For device marking beyond this, certain price adders apply. Please check with your Microchip Sales Office. For QTP devices, any special marking adders are included in QTP price.

64-Lead Plastic Thin Quad Flatpack 10x10x1 mm Body, 1.0/0.10 mm Lead Form (TQFP)



Units		INCHES			MILLIMETERS*		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		64			64	
Pitch	p		.020			0.50	
Pins per Side	n1		16			16	
Overall Height	A	.039	.043	.047	1.00	1.10	1.20
Molded Package Thickness	A2	.037	.039	.041	0.95	1.00	1.05
Standoff §	A1	.002	.006	.010	0.05	0.15	0.25
Foot Length	L	.018	.024	.030	0.45	0.60	0.75
Footprint (Reference)	(F)		.039			1.00	
Foot Angle	φ	0	3.5	7	0	3.5	7
Overall Width	E	.463	.472	.482	11.75	12.00	12.25
Overall Length	D	.463	.472	.482	11.75	12.00	12.25
Molded Package Width	E1	.390	.394	.398	9.90	10.00	10.10
Molded Package Length	D1	.390	.394	.398	9.90	10.00	10.10
Lead Thickness	c	.005	.007	.009	0.13	0.18	0.23
Lead Width	B	.007	.009	.011	0.17	0.22	0.27
Pin 1 Corner Chamfer	CH	.025	.035	.045	0.64	0.89	1.14
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MS-026
Drawing No. C04-085

NOTES:

